

MB1-130-01-F-S-01-SL

MB1-130-01-F-S-01-SL-N

(1.00 mm) .0394"

MB1 SERIES

MINI EDGE CARD SOCKET WITH GUIDES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MB1

Insulator Material:

Black LCP

Contact Material:

BeCu

Plating:

Sn or Au over
50 μ" (1.27 μm) Ni

Current Rating:

2.2 A per pin
(6 pins powered)

Operating Temp Range:

-55 °C to +125 °C

Insertion Depth:

(5.26 mm) .207" to

(6.10 mm) .240"

RoHS Compliant:

Yes

Mates with:

(0.80 mm) .031" PCB,

(1.60 mm) .062" PCB

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (20-30)

(0.15 mm) .006" max (40-50)*

*(.004" stencil solution may be available; contact IPG@samtec.com)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

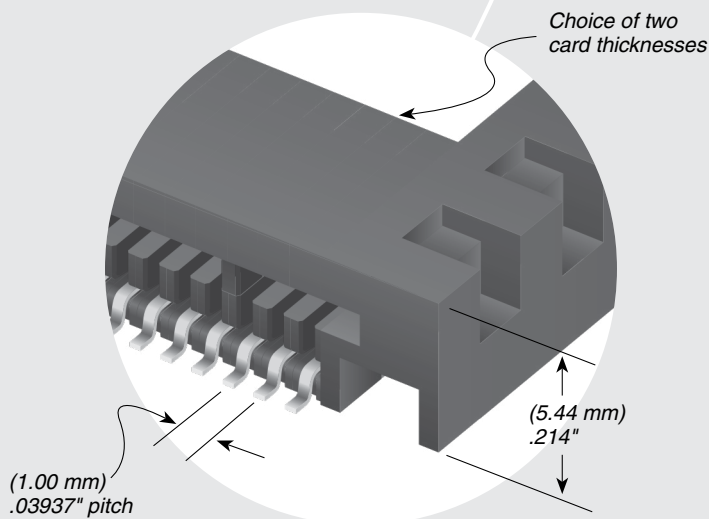


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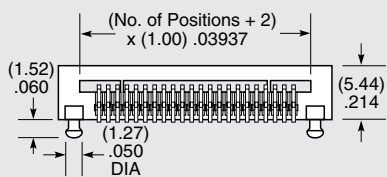
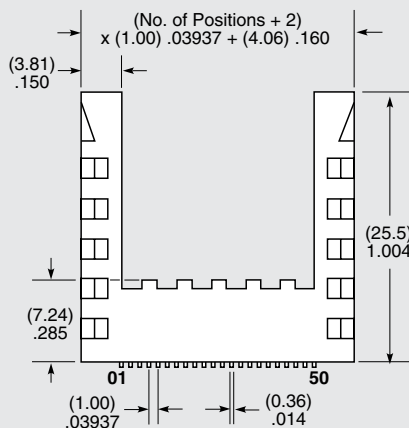
ALSO AVAILABLE (MOQ Required)

- Other platings

Note: Some sizes, styles and options are non-standard, non-returnable.



20, 30, 40, 50



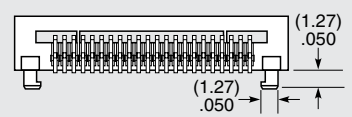
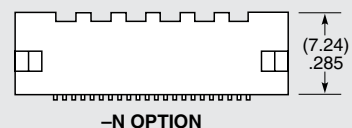
-F
= Gold flash on contact, Matte Tin on tail

-L
= 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail

Specify CARD SLOT from chart

-N
= No Card Guides

CARD SLOT	A	MATES WITH BOARD THICKNESS
-01	(0.97) .038	(0.80) .031
-02	(1.83) .072	(1.60) .062



Important Note: Samtec recommends that pads on the mating board be Gold plated.